捷多邦,专业P**SN54CBT.D3384**p/**SN74**CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025K - MAY 1995 - REVISED NOVEMBER 1998

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages, Ceramic Flat (W) Package, Ceramic DIPs (JT), and Ceramic Chip Carriers (FK)

description

The 'CBTD3384 devices provide ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switches allows connections to be made without adding propagation delay. A diode to V_{CC} is integrated on the die to allow for level shifting between 5-V inputs and 3.3-V outputs.

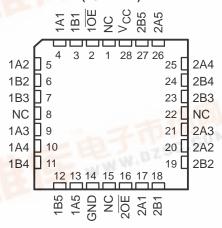
These devices are organized as two 5-bit switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on and port A is connected to port B. When \overline{OE} is high, the switch is open and a high-impedance state exists between the two ports.

The SN54CBTD3384 is characterized for operation over the full military temperature range from -55°C to 125°C. The SN74CBTD3384 is characterized for operation from -40°C to 85°C.

SN54CBTD3384 . . . JT OR W PACKAGE SN74CBTD3384 . . . DB, DBQ, DGV, DW, OR PW PACKAGE (TOP VIEW)

10E	1	0 24	Vcc
1B1 [2	23] 2B5
1A1 [3	22	2A5
1A2	4	21	2A4
1B2 [5	20	2B4
1B3 [6	19	2B3
1A3 [7	18	2A3
1A4 [8	17	2A2
1B4 [9	16	2B2
1B5 [10	15	2B1
1A5 [11	14	2A1
GND [12	13	20E

SN54CBTD3384 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE (each 5-bit bus switch)

	-	_			
INPUTS		INPUTS/OUTPUTS			
10E	2OE	1B1-1B5	2B1-2B5		
L	L	1A1-1A5	2A1-2A5		
L	Н	1A1-1A5	Z		
Н	L	Z	2A1-2A5		
Н	Н	Z	Z		

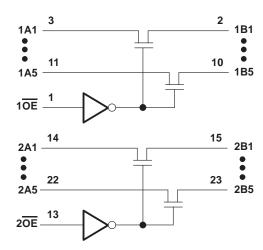
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SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

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logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, JT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (see Note 1)		0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		–50 mA
Package thermal impedance, θ _{JA} (see Note 2)	: DB package	104°C/W
	DBQ package	113°C/W
	DGV package	139°C/W
	DW package	81°C/W
	PW package	120°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		SN54CBTD3384		SN74CBT	UNIT	
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level control input voltage	2		2		V
V _{IL}	Low-level control input voltage		0.8		0.8	V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER TEST CONDITIONS		SN54CBTD3384		SN74CBTD3384			UNIT				
PAI	KAMETEK		IESI CONDII	IONS	MIN	TYP†	MAX	MIN	TYP [†]	† MAX UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$V_{CC} = 4.5 \text{ V}, I_{I} = -18 \text{ mA}$				-1.2			-1.2	V
Vон		See Figure 2									
II		$V_{CC} = 5.5 \text{ V}, V_{I} = 5.5 \text{ V or GND}$				±1			±1	μΑ	
Icc		$V_{CC} = 5.5 \text{ V}, I_O = 0, V_I = V_{CC} \text{ or GND}$				1.5			1.5	mA	
Δl _{CC} ‡	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				2.5			2.5	mA	
Ci	Control inputs	V _I = 3 V or 0			3			3		pF	
C _{io(OFF}	=)	$V_0 = 3 \text{ V or } 0,$	OE = V _{CC}			3.5			3.5		pF
			V. 0	I _I = 64 mA		5			5	7	
ron§	V _{CC} = 4.5 V	V _C C = 4.5 V	V _I = 0	I _I = 30 mA		5			5	7	Ω
			V _I = 2.4 V,	I _I = 15 mA		35			35	50	

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBTD3384		SN74CBTD3384		UNIT
			MIN	MAX	MIN	MAX	ONII
$t_{pd}\P$	A or B	B or A		0.25		0.25	ns
^t en	ŌĒ	A or B	2.2	9.7	2.3	7	ns
^t dis	ŌE	A or B	1.5	8.6	1.7	5.3	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

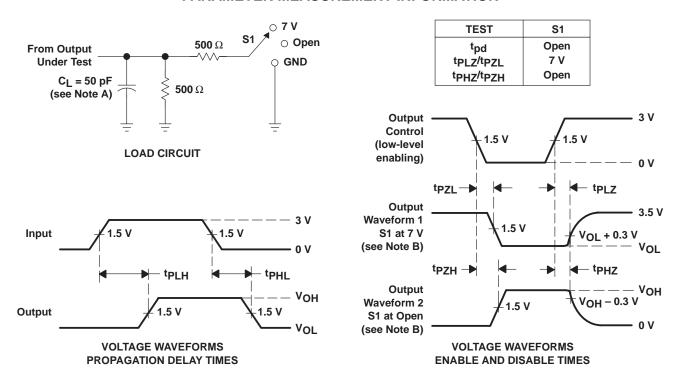


[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

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PARAMETER MEASUREMENT INFORMATION

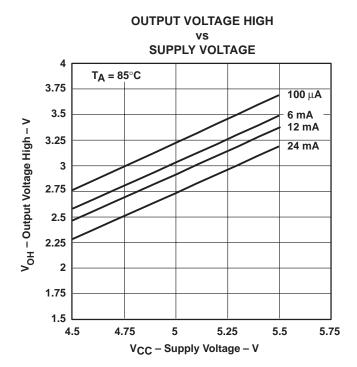


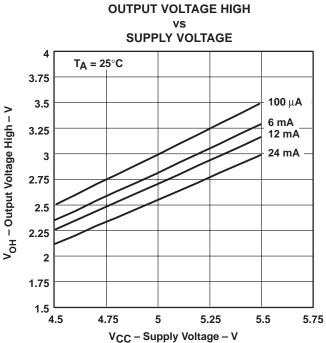
NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \, \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns,
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS





OUTPUT VOLTAGE HIGH

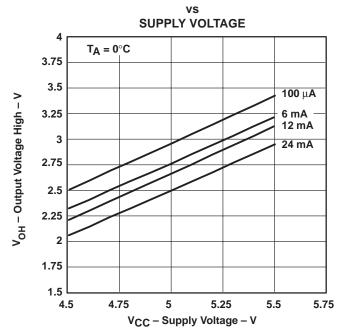


Figure 2. V_{OH} Values

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